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01/02/2002

SCS # 1089

U.S. UTILITY Patent Application

PATENT NUMBER and
ISSUE DATE

APPL NUM 10038806	FILING DATE 01/02/2002	CLASS 257	SUBCLASS	GAU 2811	EXAMINER S. V. W.
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**APPLICANTS: Takeuchi Timothy;

**CONTINUING DATA VERIFIED:

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** FOREIGN APPLICATIONS VERIFIED:

PG-PUB	DO NOT PUBLISH <input type="checkbox"/>	RESCIND <input type="checkbox"/>	ATTORNEY DOCKET NO 42P13557
Foreign priority claimed <input type="checkbox"/> yes <input type="checkbox"/> no			
35 USC 119 conditions met <input type="checkbox"/> yes <input type="checkbox"/> no			
Verified and Acknowledged Examiners's initials			
TITLE : Semiconductor package with integrated heat spreader attached to a thermally conductive substrate core			

U.S. DEPT. OF COMM./PAT. & TM.-PTO-436 (Rev. 12-93)

NOTICE OF ALLOWANCE MAILED		CLAIMS ALLOWED	
		Total Claims	Print Claims for O.G.
Assistant Examiner		DRAWING	
		Sheets Drawn	Figs. Drawn
ISSUE FEE		Print Figs.	
Amount Due	Date Paid	Application Examiner	
<input type="checkbox"/> TERMINAL DISCLAIMER		PREPARED FOR ISSUE	
		WARNING: The information disclosed herein may be restricted. Unauthorized disclosure may be prohibited by the United States Code Title 35, Sections 122, 181 and 368, Possession outside the U.S. Patent & Trademark Office is restricted to authorized employees and contractors only.	

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